- **Function and Pinout Compatible With FCT and F Logic**
- **25-Ω Output Series Resistors to Reduce Transmission-Line Reflection Noise**
- **Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Fully Compatible With TTL Input and Output Logic Levels**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**
- **12-mA Output Sink Current 15-mA Output Source Current**
- **3-State Outputs**

P, Q, OR SO PACKAGE
(TOP VIEW)

$T/\overline{R}$	1	20	V_{CC}
A_0	2	19	$\overline{OE}$
A_1	3	18	B_0
A_2	4	17	B_1
A_3	5	16	B_2
A_4	6	15	B_3
A_5	7	14	B_4
A_6	8	13	B_5
A_7	9	12	B_6
GND	10	11	B_7
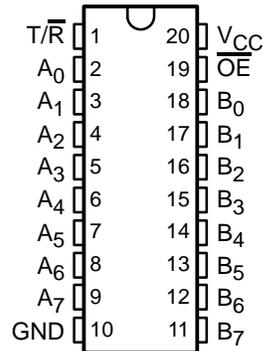
description

The CY74FCT2245T contains eight noninverting, bidirectional buffers with 3-state outputs intended for bus-oriented applications. On-chip termination resistors at the outputs reduce system noise caused by reflections. For this reason, the CY74FCT2245T can replace the CY74FCT245T in an existing design. The CY74FCT2245T current-sinking capability is 12 mA at the A and B ports.

The transmit/receive (T/R) input determines the direction of data flow through the bidirectional transceiver. Transmit (active high) enables data from A ports to B ports; receive (active low) enables data from B ports to A ports. The output-enable ($\overline{OE}$) input, when high, disables both the A and B ports by putting them in the high-impedance state.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T_A	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	QSOP – Q	Tape and reel	4.1	CY74FCT2245CTQCT	FCT2245
	SOIC – SO	Tube	4.1	CY74FCT2245CTSOC	FCT2245
		Tape and reel	4.1	CY74FCT2245CTSOCT	
	DIP – P	Tube	4.6	CY74FCT2245ATPC	74FCT2245ATPC
	QSOP – Q	Tape and reel	4.6	CY74FCT2245ATQCT	FCT2245A
	SOIC – SO	Tube	4.6	CY74FCT2245ATSOC	FCT2245A
		Tape and reel	4.6	CY74FCT2245ATSOCT	
	QSOP – Q	Tape and reel	7.0	CY74FCT2245TQCT	FCT2245
	SOIC – SO	Tube	7.0	CY74FCT2245TSOC	FCT2245
		Tape and reel	7.0	CY74FCT2245TSOCT	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

FUNCTION TABLE

INPUTS		OUTPUT
$\overline{\text{OE}}$	T/$\overline{\text{R}}$	
L	L	Bus B data to bus A
L	H	Bus A data to bus B
H	X	Z

H = High logic level, L = Low logic level,
X = Don't care, Z = High-impedance state

logic diagram (positive logic)

To Seven Other Channels
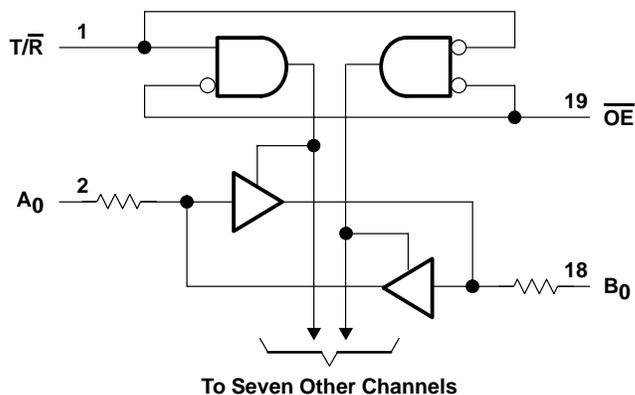
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	....	−0.5 V to 7 V
DC input voltage range	....	−0.5 V to 7 V
DC output voltage range	....	−0.5 V to 7 V
DC output current (maximum sink current/pin)	....	120 mA
Package thermal impedance, θ_{JA} (see Note 1): P package	....	69°C/W
Q package	....	68°C/W
SO package	....	58°C/W
Ambient temperature range with power applied, T_A	....	−65°C to 135°C
Storage temperature range, T_{stg}	....	−65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1:   The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			−15	mA
I_{OL}	Low-level output current			12	mA
T_A	Operating free-air temperature	−40		85	°C

NOTE 2:   All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP[†]	MAX	UNIT
V_{IK}	V_{CC} = 4.75,	I_{IN} = −18 mA			−0.7	−1.2	V
V_{OH}	V_{CC} = 4.75,	I_{OH} = −15 mA		2.4	3.3		V
V_{OL}	V_{CC} = 4.75,	I_{OL} = 12 mA			0.3	0.55	V
R_{out}	V_{CC} = 4.75,	I_{OL} = 12 mA		20	25	40	Ω
V_{hys}	All inputs				0.2		V
I_I	V_{CC} = 5.25 V,	$V_{IN} = V_{CC}$				5	μA
I_{IH}	V_{CC} = 5.25 V,	V_{IN} = 2.7 V				±1	μA
I_{IL}	V_{CC} = 5.25 V,	V_{IN} = 0.5 V				±1	μA
I_{OZH}	V_{CC} = 5.25 V,	V_{OUT} = 2.7 V				10	μA
I_{OZL}	V_{CC} = 5.25 V,	V_{OUT} = 0.5 V				−10	μA
I_{OS}[‡]	V_{CC} = 5.25 V,	V_{OUT} = 0 V		−60	−120	−225	mA
I_{off}	V_{CC} = 0 V,	V_{OUT} = 4.5 V				±1	μA
I_{CC}	V_{CC} = 5.25 V,	$V_{IN} \leq$ 0.2 V,	$V_{IN} \geq V_{CC}$ − 0.2 V		0.1	0.2	mA
ΔI_{CC}	V_{CC} = 5.25 V, V_{IN} = 3.4 V[§], f_1 = 0, Outputs open				0.5	2	mA
I_{CCD}[¶]	V_{CC} = 5.25 V, One input switching at 50% duty cycle, Outputs open, T/R̄ = OE̅ = GND, $V_{IN} \leq$ 0.2 V or $V_{IN} \geq V_{CC}$ − 0.2 V				0.06	0.12	mA/MHz
I_C[#]	V_{CC} = 5.25 V, Outputs open, T/R̄ = OE̅ = GND	One input switching at f_1 = 10 MHz at 50% duty cycle	$V_{IN} \leq$ 0.2 V or $V_{IN} \geq V_{CC}$ − 0.2 V		0.7	1.4	mA
			V_{IN} = 3.4 V or GND		1	2.4	
		Eight bits switching at f_1 = 2.5 MHz at 50% duty cycle	$V_{IN} \leq$ 0.2 V or $V_{IN} \geq V_{CC}$ − 0.2 V		1.3	2.6[‖]	
			V_{IN} = 3.4 V or GND		3.3	10.6[‖]	
C_i					5	10	pF
C_o					9	12	pF

[†] Typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

[§] Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

[¶] This parameter is derived for use in total power-supply calculations.

[#] I_C $= I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

- I_C = Total supply current
- I_{CC} = Power-supply current with CMOS input levels
- ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)
- D_H = Duty cycle for TTL inputs high
- N_T = Number of TTL inputs at D_H
- I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)
- f_0 = Clock frequency for registered devices, otherwise zero
- f_1 = Input signal frequency
- N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

[‖] Values for these conditions are examples of the I_{CC} formula.

CY74FCT2245T
8-BIT TRANSCEIVER
WITH 3-STATE OUTPUTS

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT2245T		CY74FCT2245AT		CY74FCT2245CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A_n or B_n	B_n or A_n	1.5	7	1.5	4.6	1.5	4.1	ns
t_{PHL}			1.5	7	1.5	4.6	1.5	4.1	
t_{PZH}	$\overline{OE}$	A or B	1.5	9.5	1.5	6.2	1.5	5.8	ns
t_{PZL}			1.5	9.5	1.5	6.2	1.5	5.8	
t_{PHZ}	$\overline{OE}$	A or B	1.5	7.5	1.5	5	1.5	4.5	ns
t_{PLZ}			1.5	7.5	1.5	5	1.5	4.5	

TEXAS INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR
3-STATE OUTPUTS

VOLTAGE WAVEFORMS
PULSE DURATION

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING
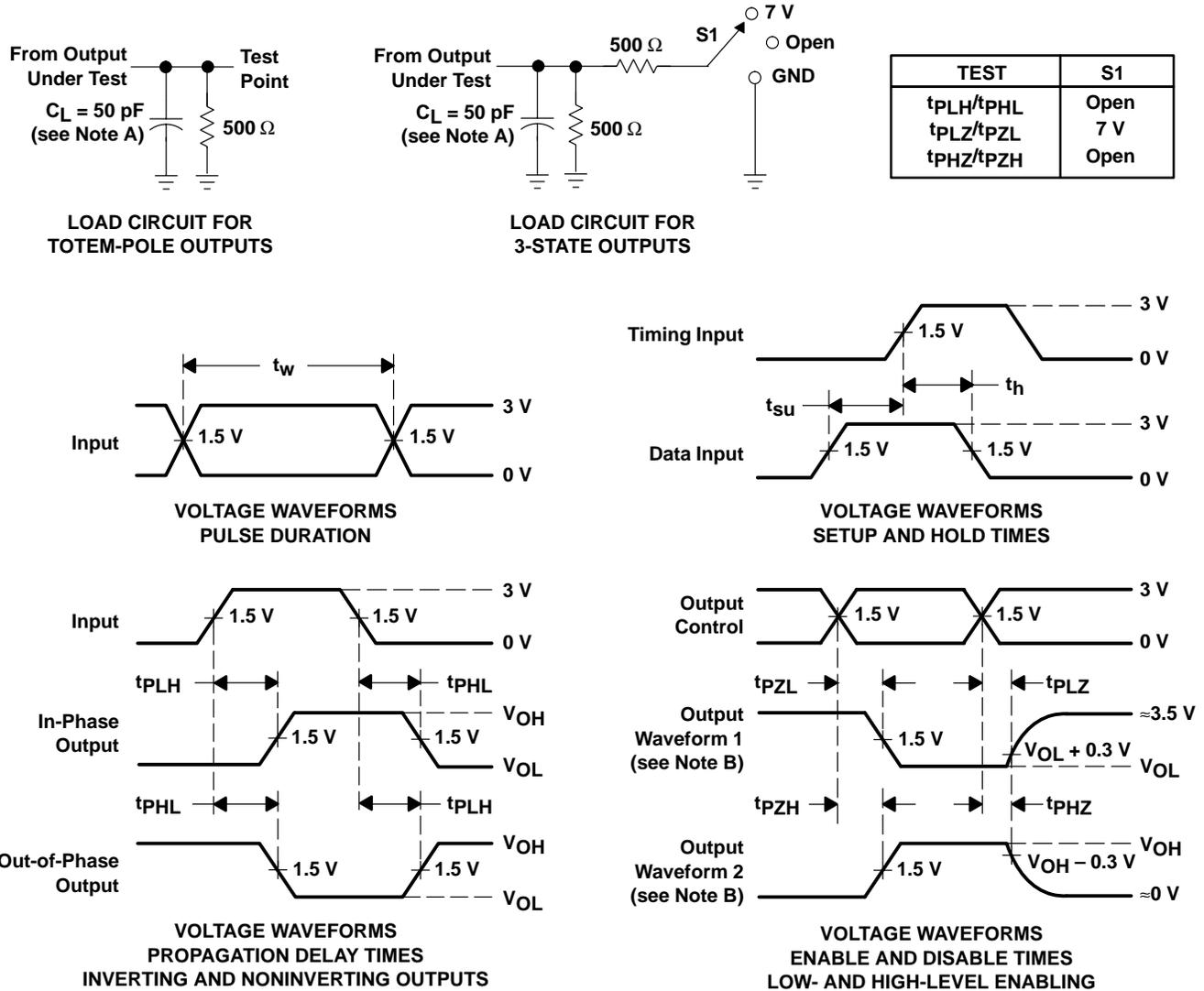
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
74FCT2245ATSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT2245ATSOCTG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT2245CTSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT2245CTSOCTG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245ATPC	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT2245ATPCE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT2245ATPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245ATPWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245ATPWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245ATQCT	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT2245ATQCTE4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT2245ATQCTG4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT2245ATSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245ATSOCE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245ATSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245ATSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245CTQCT	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT2245CTQCTE4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT2245CTQCTG4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT2245CTSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245CTSOCE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245CTSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245CTSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245TQCT	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT2245TQCTG4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
CY74FCT2245TSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245TSOCE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245TSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245TSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245TSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT2245TSOCTG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL BOX INFORMATION

REEL DIMENSIONS
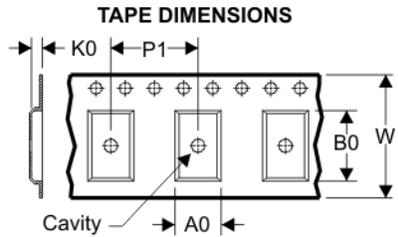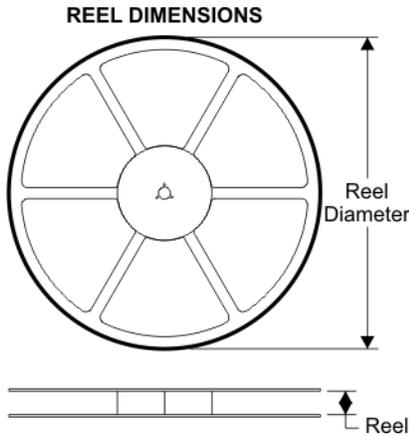

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE
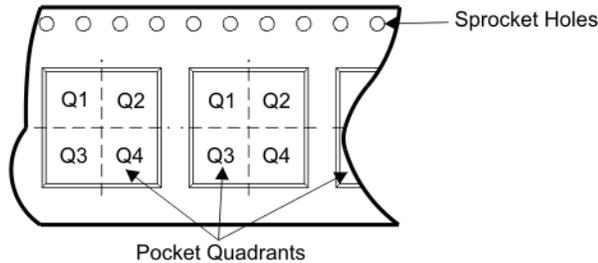
Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT2245ATPWR	PW	20	SITE 41	330	16	6.95	7.1	1.6	8	16	Q1
CY74FCT2245ATQCT	DBQ	20	SITE 41	330	16	6.5	9.0	2.1	8	16	Q1
CY74FCT2245ATSOCT	DW	20	SITE 41	330	24	10.8	13.0	2.7	12	24	Q1
CY74FCT2245CTQCT	DBQ	20	SITE 41	330	16	6.5	9.0	2.1	8	16	Q1
CY74FCT2245CTSOCT	DW	20	SITE 41	330	24	10.8	13.0	2.7	12	24	Q1
CY74FCT2245TQCT	DBQ	20	SITE 41	330	16	6.5	9.0	2.1	8	16	Q1
CY74FCT2245TSOCT	DW	20	SITE 41	330	24	10.8	13.0	2.7	12	24	Q1

TAPE AND REEL BOX DIMENSIONS
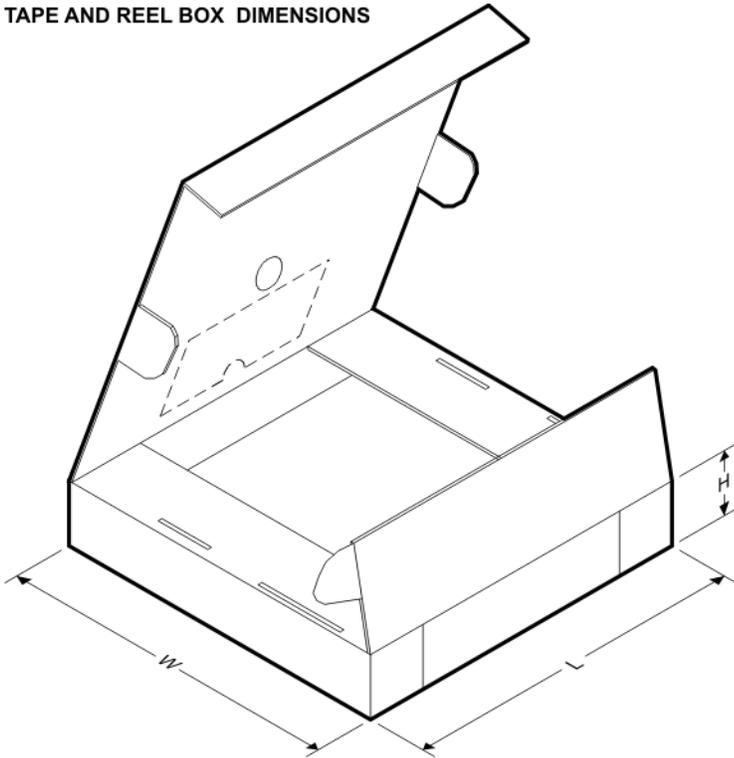
Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
CY74FCT2245ATPWR	PW	20	SITE 41	346.0	346.0	33.0
CY74FCT2245ATQCT	DBQ	20	SITE 41	346.0	346.0	33.0
CY74FCT2245ATSOCT	DW	20	SITE 41	346.0	346.0	41.0
CY74FCT2245CTQCT	DBQ	20	SITE 41	346.0	346.0	33.0
CY74FCT2245CTSOCT	DW	20	SITE 41	346.0	346.0	41.0
CY74FCT2245TQCT	DBQ	20	SITE 41	346.0	346.0	33.0
CY74FCT2245TSOCT	DW	20	SITE 41	346.0	346.0	41.0

N (R−PDIP−T**)
16 PINS SHOWN

PLASTIC DUAL−IN−LINE PACKAGE

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
C MS−001 VARIATION	AA	BB	AC	AD

A

0.260 (6,60)
0.240 (6,10)

0.070 (1,78)
0.045 (1,14) D

0.045 (1,14)
0.030 (0,76) D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) M

14/18 Pin Only
20 Pin vendor option D

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
        D. The 20 pin end lead shoulder width is a vendor option, either half or full width.
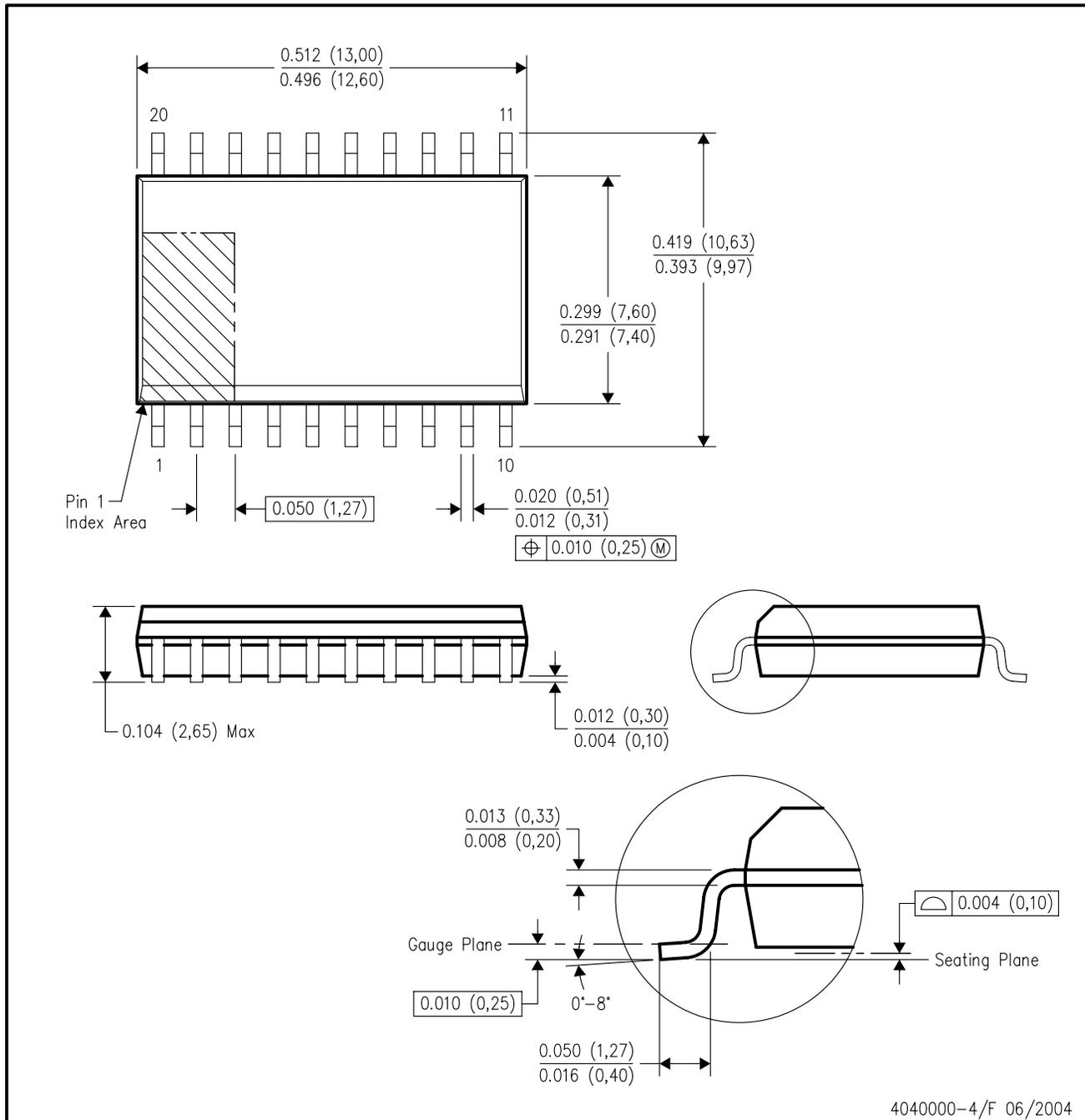
TEXAS
INSTRUMENTS
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DW (R−PDSO−G20)   PLASTIC SMALL−OUTLINE PACKAGE

0.512 (13,00)
0.496 (12,60)

0.419 (10,63)
0.393 (9,97)

0.299 (7,60)
0.291 (7,40)

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

Pin 1
Index Area

0.104 (2,65) Max

0.012 (0,30)
0.004 (0,10)

0.013 (0,33)
0.008 (0,20)

Gauge Plane

0.010 (0,25)

0°−8°

0.004 (0,10)

Seating Plane

0.050 (1,27)
0.016 (0,40)

4040000−4/F 06/2004

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
        D. Falls within JEDEC MS−013 variation AC.

TEXAS
INSTRUMENTS
www.ti.com

DBQ (R−PDSO−G20)　　　　　　　　PLASTIC SMALL−OUTLINE PACKAGE

$\dfrac{0.344\ (8,75)}{0.337\ (8,55)}$

20

11

$\dfrac{0.244\ (6,20)}{0.228\ (5,80)}$

$\dfrac{0.157\ (4,00)}{0.150\ (3,80)}$

1

10

Pin 1
Index Area

0.025 (0,635)

$\dfrac{0.012\ (0,30)}{0.008\ (0,20)}$

⊕ | 0.005 (0,13) Ⓜ

0.069 (1,75) Max

$\dfrac{0.010\ (0,25)}{0.004\ (0,10)}$

$\dfrac{0.010\ (0,25)}{0.006\ (0,15)}$

Gauge Plane

0.004 (0,10)

Seating Plane

0.010 (0,25)

0°−8°

$\dfrac{0.035\ (0,89)}{0.016\ (0,40)}$

4073301−3/G 02/2005

NOTES:　A.　All linear dimensions are in inches (millimeters).
　　　　　B.　This drawing is subject to change without notice.
　　　　　C.　Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
　　　　　D.　Falls within JEDEC MO−137 variation AD.

MECHANICAL DATA

PW (R-PDSO-G**) 　　　　　　　　　**PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN

DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60
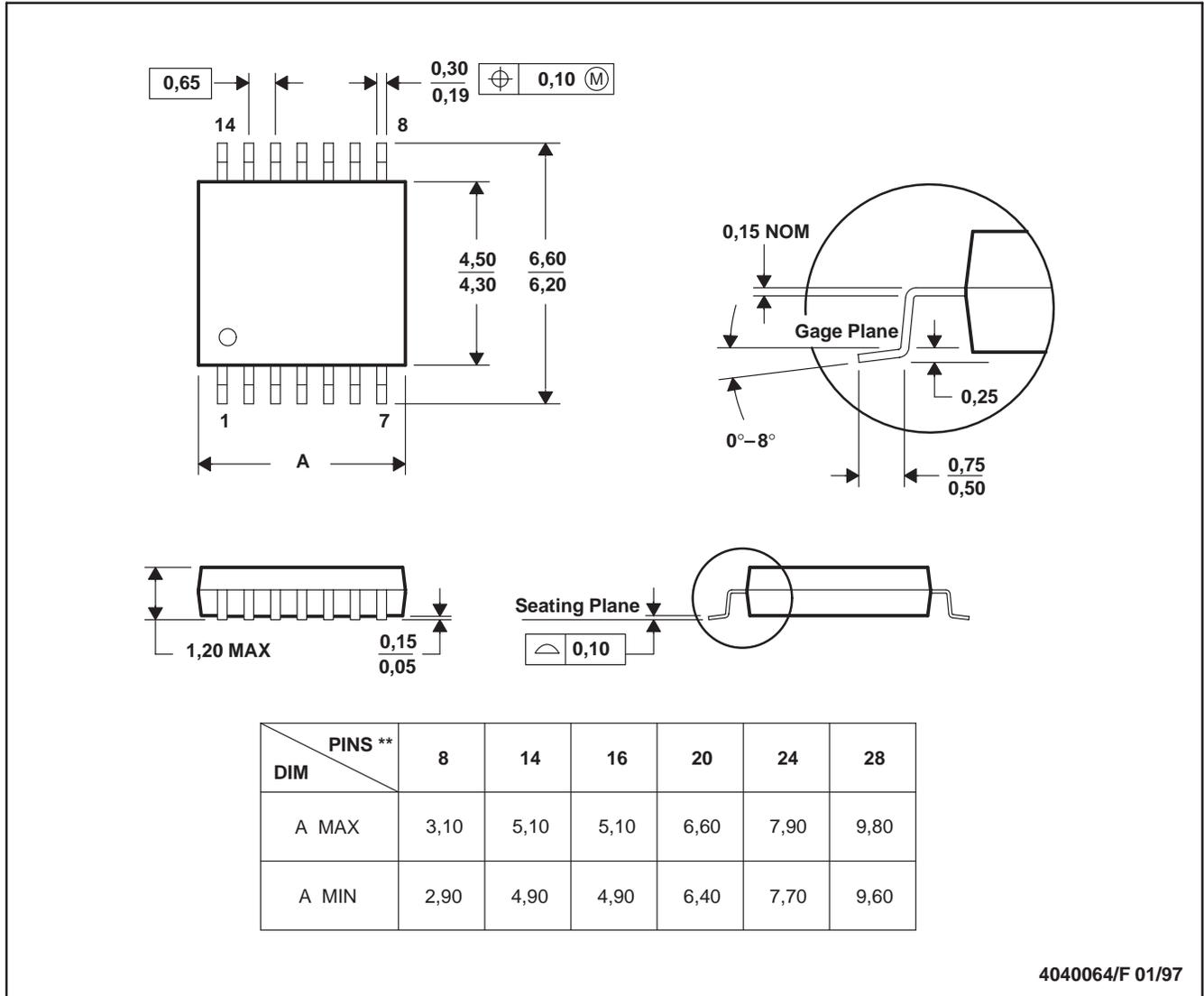
4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

TEXAS INSTRUMENTS
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